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### IN THE CLAIMS

Please amend the claims as follows.

1. (Currently Amended) A substrate to mount a die having at least one input signal terminal, the substrate keeping an impedance variation between an input signal entering the substrate from a receiving substrate and an output signal provided to the at least one input terminal below a predetermined value, the substrate comprising:

A substrate to mount a die having a plurality of terminals, the substrate comprising:

a dielectric core member having an example thickness of 800 microns;

a first plurality of dielectric lamination layers on a first side of the core member, each having an example thickness of 30 microns, and wherein the dielectric core member comprises material of different dielectric permittivity in comparison to a permittivity of material of the dielectric lamination layers;

a second plurality of conductive layers on the first side of the core member, each having an example thickness of 25 microns, and including at least one connector ~~a plurality of ball-grid array (BGA) connectors~~ on a first surface of an uppermost one of the second plurality of conductive layers to couple to the at least one input signal terminal ~~corresponding terminals~~ of the die; and

a single conductive layer on a ~~a~~ [[the]] second side of the core member, having an example thickness of 17 microns, wherein the single conductive layer comprises at least one land ~~a plurality of lands;~~ and to couple to the input signal from the receiving substrate ~~a plurality of solder balls, coupled to corresponding ones of the plurality of lands, to couple to corresponding terminals of a receiving substrate.~~

2-7. (Canceled)

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8. (Currently amended) A system comprising:
- a die having a plurality of terminals, including at least one input signal terminal;
  - a receiving substrate having a plurality of terminals, including at least one terminal to provide an input signal;
  - a layered substrate including
    - a dielectric core member;
    - a first plurality of dielectric lamination layers on a first side of the core member, wherein the dielectric core member comprises material of different dielectric permittivity in comparison to a permittivity of material of the dielectric lamination layers;
    - a second plurality of conductive layers on the first side of the core member, including at least one connector ~~a plurality of ball-grid array connectors~~ on a first surface of an uppermost one of the second plurality of conductive layers, the connector being coupled to the at least one input signal terminal ~~connectors being coupled to corresponding terminals of the die;~~ and
    - a single conductive layer on a [[the]] second side of the core member, wherein the single conductive layer comprises at least one land coupled to the input signal from the receiving substrate ~~a plurality of lands;~~ and
    - ~~a plurality of solder balls, coupled between ones of the plurality of lands and corresponding terminals of the receiving substrate.~~
- 9-25. (Canceled)
26. (Previously Presented) The substrate as claimed in claim 1, wherein the receiving substrate comprises one of an interposer or a motherboard.
27. (Previously Presented) The system as claimed in claim 8, wherein the receiving substrate comprises one of an interposer or a motherboard.
28. (New) The substrate as claimed in claim 1, wherein the predetermined value is within the range of  $\pm 10$  ohms.

29. (New) The system as claimed in claim 8, wherein the predetermined value is within the range of  $\pm 10$  ohms.

30. (New) The system as claimed in claim 8, wherein the dielectric core member has an example thickness of 800 microns, wherein each of the first plurality of dielectric lamination layers has an example thickness of 30 microns, wherein each of the second plurality of conductive layers has an example thickness of 25 microns, and wherein the single conductive layer has an example thickness of 17 microns.

31. (New) A substrate to mount a die having at least one input signal terminal, the substrate keeping an impedance variation between an input signal entering the substrate from a receiving substrate and an output signal provided to the at least one input terminal below a predetermined value, the substrate comprising:

- a dielectric core member;

- a first plurality of dielectric lamination layers on a first side of the core member, wherein the dielectric core member comprises material of different dielectric permittivity in comparison to a permittivity of material of the dielectric lamination layers;

- a second plurality of conductive layers on the first side of the core member, including at least one connector on a first surface of an uppermost one of the second plurality of conductive layers to couple to the at least one input signal terminal of the die; and

- a single conductive layer on a second side of the core member, wherein the single conductive layer comprises at least one land to couple to the input signal from the receiving substrate.

32. (New) The substrate as claimed in claim 31, wherein the receiving substrate comprises one of an interposer or a motherboard.

33. (New) The substrate as claimed in claim 32, wherein the predetermined value is within the range of  $\pm 10$  ohms.

34. (New) The substrate as claimed in claim 33, wherein the dielectric core member has an example thickness of 800 microns, wherein each of the first plurality of dielectric lamination layers has an example thickness of 30 microns, wherein each of the second plurality of conductive layers has an example thickness of 25 microns, and wherein the single conductive layer has an example thickness of 17 microns.